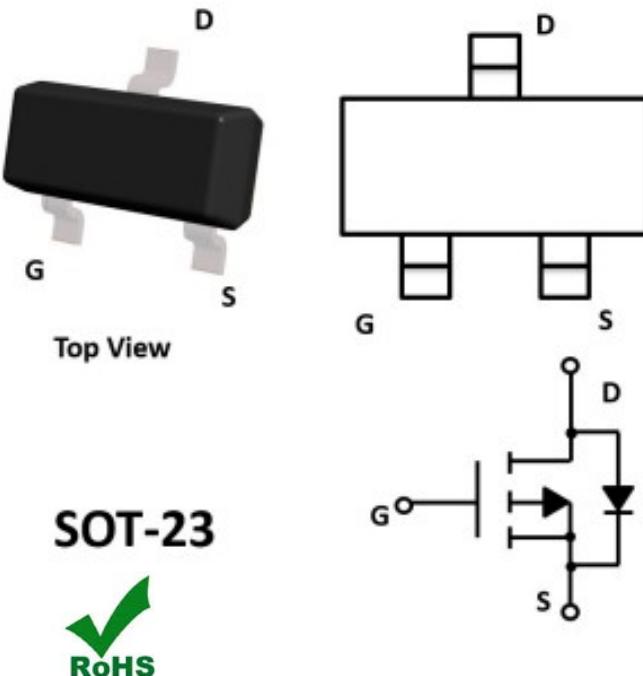


P-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} -20V
- I_D -2A
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) <94 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-2.5V$) <127 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-1.8V$) <187 mohm

General Description

- Trench Power LV MOSFET technology
- Low $R_{DS(ON)}$
- Low Gate Charge

Applications

- Video monitor
- Power management

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	V_{DS}	-20	V
Gate-source Voltage	V_{GS}	± 10	V
Drain Current <small>$T_A=25^\circ\text{C}$ @ Steady State</small>	I_D	-2	A
		-1.6	
Pulsed Drain Current ^A	I_{DM}	-8	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$	P_D	0.7	W
Thermal Resistance Junction-to-Ambient ^B	R_{JJA}	178	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ\text{C}$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
ELV20152RPO	F2	E152RP	3000	30000	120000	7 "reel

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$		-1		μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 10\text{V}, V_{\text{DS}}=0\text{V}$		± 100		nA
Gate Threshold Voltage	V_{GTH}	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.4	-0.62	-1.0	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}= -4.5\text{V}, I_{\text{D}}=-1.5\text{A}$		81	94	$\text{m}\Omega$
		$V_{\text{GS}}= -2.5\text{V}, I_{\text{D}}=-1.5\text{A}$		109	127	
		$V_{\text{GS}}= -1.8\text{V}, I_{\text{D}}=-1.5\text{A}$		152	187	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=2\text{A}, V_{\text{GS}}=0\text{V}$		-0.8	-1.2	V
Maximum Body-Diode Continuous Current	I_{S}			-2		A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		327		pF
Output Capacitance	C_{oss}			62		
Reverse Transfer Capacitance	C_{trs}			55		
Switching Parameters						
Total Gate Charge	Q_g	$V_{\text{GS}}=-4.5\text{V}, V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-2\text{A}$		4.5		nC
Gate Source Charge	Q_{gs}			0.85		
Gate Drain Charge	Q_{gd}			1.4		
Reverse Recovery Charge	Q_r	$I_F=-2\text{A}, dI/dt=100\text{A/us}$		2.3		ns
Reverse Recovery Time	t_r			27		
Turn-on Delay Time	$t_{\text{D(on)}}$			6		
Turn-on Rise Time	t_r	$V_{\text{GS}}=-4.5\text{V}, V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-1\text{A}, R_{\text{GEN}}=2.5\Omega$		30		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			45		
Turn-off Fall Time	t_f			46		

A. A.Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

■ Typical Performance Characteristics

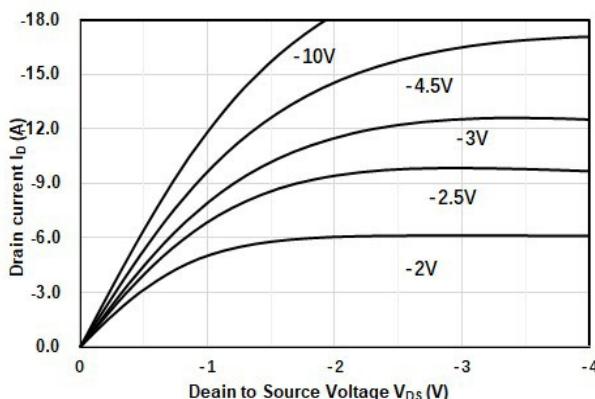


Figure1. Output Characteristics

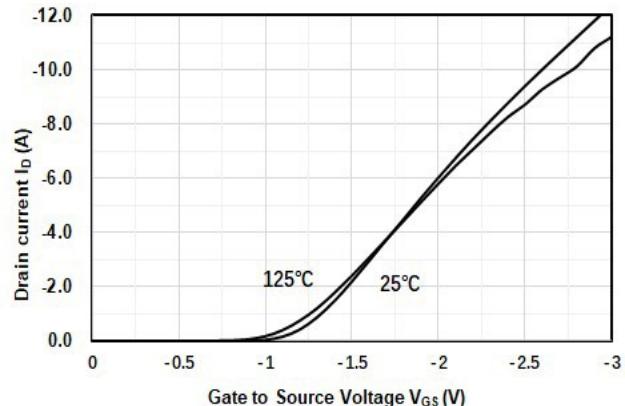


Figure2. Transfer Characteristics

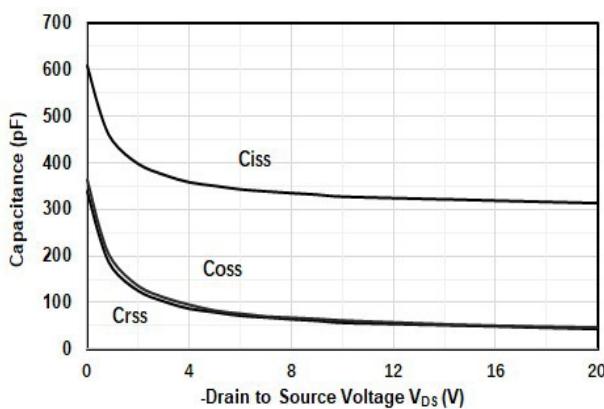


Figure3. Capacitance Characteristics

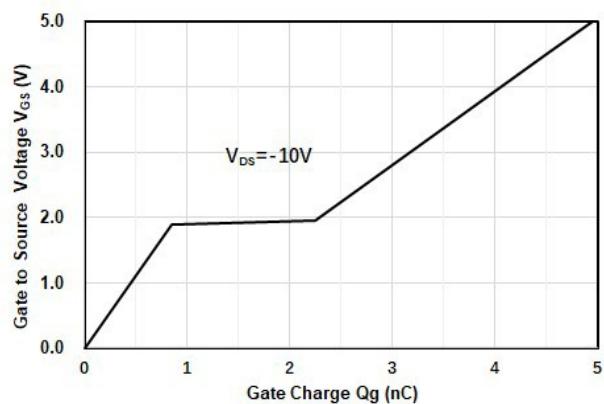


Figure4. Gate Charge

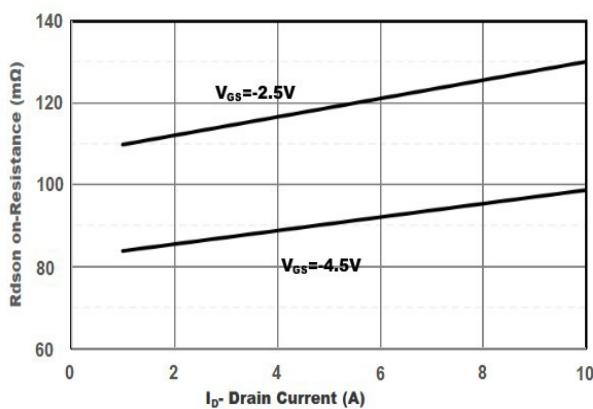


Figure5. Drain-Source on Resistance

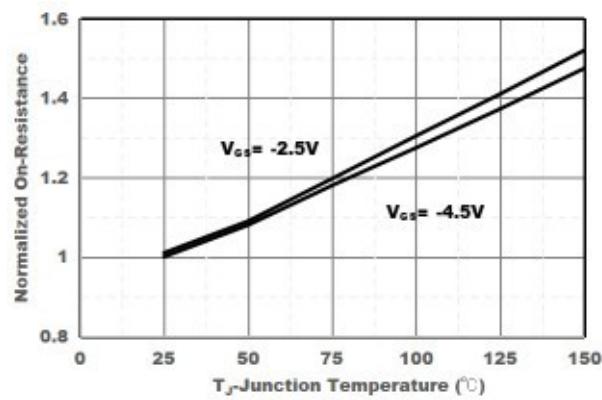


Figure6. Drain-Source on Resistance

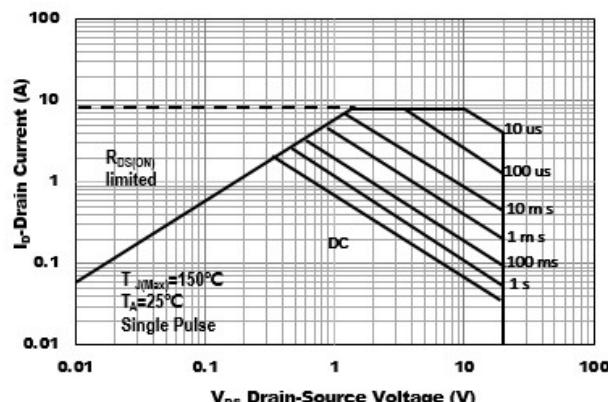


Figure 7. Safe Operation Area

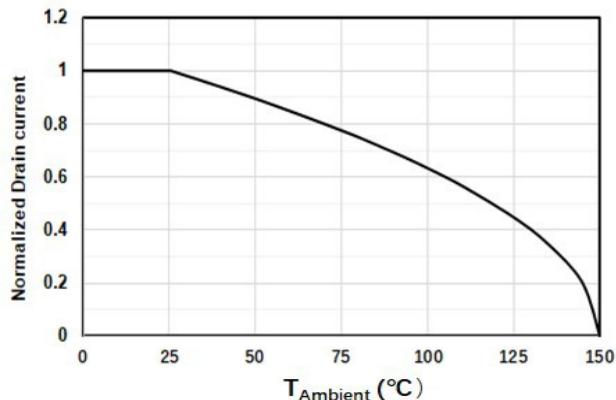


Figure 8. Drain Current vs Ambient temperature

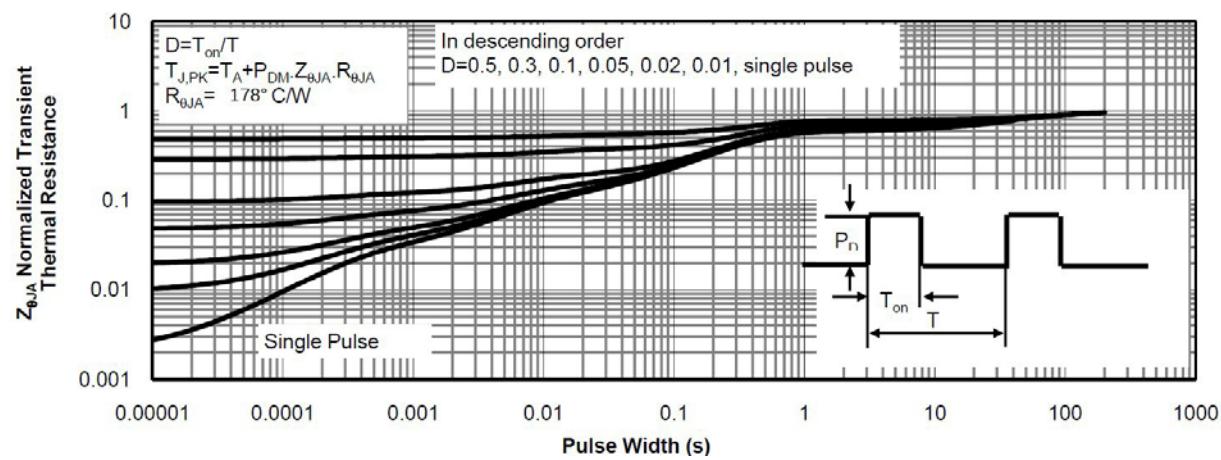


Figure 9. Normalized Maximum Transient Thermal Impedance

- SOT-23 Package information

